RM505

TECHNICAL DATA BULLETIN

GRADE: RM505   **NEMA LI 1-1998 GRADE: G-5**   **U.L. LISTED: N**

DESCRIPTION: Rolled and Molded Rods made from a plain weave, medium weight glass fabric combined with a melamine resin system. RM505 is used for mechanical and electrical applications, at low voltages. It has very good thermal and arc resistance properties. RM505 meets ANSI/NEMA IM 60000-2021 Grade G-5, MIL-I-24768/8 GMG and ASTM D709 Type IV Grade G-5.

TYPICAL PROPERTIES

		UNITS	VALUE [1]		
			Diameter Tested		
			0.500″		
PHYSICAL PROPERTIES					
Specific Gravity		-		1.95	
Rockwell Hardness		M Scale		110	
Moisture Absorption	Condition D_1-24/23	%		0.70	
Flexural Strength	Condition A	psi		54,500	
Tensile Strength	Condition A	psi		32,300	
Compressive Strength	Condition A	psi		60,900	
THERMAL PROPERTIES					
Temperature Index [2] Electrical / Mechanical		°C		120 / 140	
Flammability Rtg. (UL 94) Condition A		Class		V-0	

[1] All testing performed to ASTM D-349 unless otherwise indicated.

[2] NEMA LI-6: This temperature is a recommendation only, and based upon experience in various applications. The maximum operating temperature is dependent upon the application and should be investigated prior to use.

This data, while believed to be accurate and based on reliable analytical methods, is for informational purposes only. The terms and conditions of the agreement under which it is sold will govern any sales of this product. Data supplied above are "typical values"; not to be considered "specification values".

To assure the material's performance is adequate for a specific application; customers should verify, independent of Norplex-Micarta, performance characteristics of interest.

It is the responsibility of the users of this information to make sure that they have the latest version of this TDB, and are urged to contact Customer Service, or preferably our web site, www.norplex-micarta.com, to determine if information is the most current.

Specification writers: Contact Norplex-Micarta for specification values before submission.